12258956

CH \$40,00

PATENT ASSIGNMENT

Electronic Version v1.1 Stylesheet Version v1.1

SUBMISSION TYPE:	NEW ASSIGNMENT
NATURE OF CONVEYANCE:	ASSIGNMENT

CONVEYING PARTY DATA

Name	Execution Date
De Yuan Xiao	10/31/2008
Guo Qing Chen	10/26/2001

RECEIVING PARTY DATA

Name:	Semiconductor Manufacturing International (Shanghai) Corporation			
Street Address:	18 Zhang Jiang Road			
Internal Address:	Pudong New Area			
City:	Shanghai			
State/Country:	CHINA			
Postal Code:	201203			

PROPERTY NUMBERS Total: 1

Property Type	Number
Application Number:	12258956

CORRESPONDENCE DATA

Fax Number: (650)326-2422

Correspondence will be sent via US Mail when the fax attempt is unsuccessful.

Phone: 415-576-0200

Email: mtejera@kilpatricktownsend.com

Correspondent Name: KILPATRICK TOWNSEND AND STOCKTON LLP

Address Line 1: Two Embarcadero Center

Address Line 2: Eighth Floor

Address Line 4: San Francisco, CALIFORNIA 94111

ATTORNEY DOCKET NUMBER:	021653-024600US
NAME OF SUBMITTER:	Dah-Bin Kao

Total Attachments: 7

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<u>PATENT</u>

Docket No.: 021653-024600US Client Ref. No.: 2005-00591-SH-US

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re application of:

DE YUAN XIAO et al.

Application No.: 12/258,956

Filed: October 27, 2008

For: METHOD AND SYSTEM FOR FORMING CONDUCTIVE BUMPING WITH COPPER INTERCONNECTION

Customer No.: 20350

Confirmation No.: 1027

Examiner:

Chris C Chu

Art Unit:

2815

COMMUNICATION
REGARDING ASSIGNMENT
OF PATENT APPLICATION

Commissioner for Patents P.O. Box 1450 Alexandria, VA 22313-1450

Commissioner:

Submitted for recordation is executed assignment of this Application by one of the two inventors: De Yuan Xiao.

The second inventor, Mr. Guo Qing Chen, no longer works at Semiconductor Manufacturing International (Shanghai) Corporation (SMIC) and cannot be reached for signing the declaration and assignment of this Application. A petition under 37 C.F.R. §147(a) for non-signing inventor was filed on behalf of Mr. Guo Qing Chen. The petition was granted July 13, 2009. In addition, Mr. Guo Qing Chen has conveyed the right of all his company-related inventions to Semiconductor Manufacturing International (Shanghai) Corporation (SMIC) in an EMPLOYEE INTELLECTUAL PROPERTY RIGHT AGREEMENT. A Chinese version of the agreement signed by Mr. Mr. Guo Qing Chen is hereby submitted for recordation. Also submitted is an English version of the agreement provided by SMIC.

<u>PATENT</u>

DE YUAN XIAO et al. Application No.: 12/258,956

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If the Examiner believes a telephone conference would expedite prosecution of this application, please telephone the undersigned at (650) 326-2400.

Respectfully submitted,

/Dah-Bin Kao/

Dah-Bin Kao Reg. No. 53,092

KILPATRICK TOWNSEND & STOCKTON LLP Two Embarcadero Center, Eighth Floor San Francisco, California 94111-3834 Tel: (415) 576-0200 Fax: (415) 576-0300 DBK:mtt

63228137 v1

Attorney Docket No.: 021653-024600US

Client Reference No.: I-05-591

ASSIGNMENT OF PATENT APPLICATION

JOINT

WHEREAS, De Yuan Xiao of 18 Zhang Jiang Rd., Pudong New Area, Shanghai, 201203 People's Republic of China; and Guo Qing Chen of 18 Zhang Jiang Rd., Pudong New Area, Shanghai, 201203 People's Republic of China, hereinafter referred to as "Assignors," are the inventors of the invention described and set forth in the below-identified application for United States Letters Patent:

Title of Invention:

METHOD AND SYSTEM FOR FORMING CONDUCTIVE BUMPING WITH COPPER

INTERCONNECTION

Date(s) of execution of Declaration:

Filing Date:

Application No.:

; and

WHEREAS, Semiconductor Manufacturing International (Shanghai) Corporation, a corporation of People's Republic of China, located at 18 Zhang Jiang Rd, Pudong New Area, Shanghai, 201203, People's Republic of China, hereinafter referred to as "ASSIGNEE," is desirous of acquiring an interest in the invention and application and in any U.S. Letters Patent and Registrations which may be granted on the same;

For good and valuable consideration, receipt of which is hereby acknowledged by Assignors, Assignors have assigned, and by these presents do assign to Assignee all right, title and interest in and to the invention and application and to all foreign counterparts (including patent, utility model and industrial designs), and in and to any Letters Patent and Registrations which may hereafter be granted on the same in the United States and all countries throughout the world, and to claim the priority from the application as provided by the Paris Convention. The right, title and interest is to be held and enjoyed by Assignee and Assignee's successors and assigns as fully and exclusively as it would have been held and enjoyed by Assignors had this Assignment not been made, for the full term of any Letters Patent and Registrations which may be granted thereon, or of any division, renewal, continuation in whole or in part, substitution, conversion, reissue, prolongation or extension thereof.

Assignors further agree that they will, without charge to Assignee, but at Assignee's expense, (a) cooperate with Assignee in the prosecution of U.S. Patent applications and foreign counterparts on the invention and any improvements, (b) execute, verify, acknowledge and deliver all such further papers, including patent applications and instruments of transfer, and (c) perform such other acts as Assignee lawfully may request to obtain or maintain Letters Patent and Registrations for the invention and improvements in any and all countries, and to vest title thereto in Assignee, or Assignee's successors and assigns.

Assignors hereby authorize and request Townsend and Townsend and Crew LLP, Two Embarcadero Center, Eighth Floor, San Francisco, CA 94111-3834, to insert herein above the application number and filing date of said application when known.

	IN TEST	IMONY WHER	EOF, Assı	gnors have si	gned their name	s on the dates:	indicated	l.
Dated:	Ort. 31.	2008			OCH	Can	Xi	CL
					De Yuan Xiao)	_	
Dated:							-	
					Guo Qing Che	n		

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Semiconductor Manufacturing International Corporation 中芯国际集成电路制造(上海)有限公司

智能财产所属权同意书

- 半导体装置、设备、器件或方法方面,设计或发展。
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- 制造方法方面之改良
- 在半导体工业或科学领域,任何形式的智力开发中之理论或实践上的发明发展。

我同意 SMIC 有完全之所属权,可以由 SMIC 使用安排和处理。即使我离开 SMIC 之 (至少两年)年之内,相关(上述之项目)之创造仍然属于 SMIC 所有。(SMIC 将按您发明成果贡献大小给予奖励)

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我同意不侵占他人的知识产权,未经履行合法手续不得非法使用他人的知识产权(包括资料、文件或任何与 Pr 有关的智力成果)。我决不能抄袭、仿效、侵害、复制第三人的专利权、商标专用权、著作权或任何违反法律的行为。

签名: 【4】 日期: 10/26/2001

**本同意书须于寄回聘书日、报到日、试用期满日各签认一次。

PATENT

REEL: 026025 FRAME: 0400

Semiconductor Manufacturing Int'l (Shanghai) Corporation INTELLECTURAL PROPERTY RIGHT AGREEMENT

I, ______, as an employee of Semiconductor Manufacturing Int'I (Shanghai)

Corporation (SMIC), agree that: any invention-creation which is made by me and is related to business of the company belongs to the company. I have no right in said invention-creation at all. Said invention-creation includes:

- ① design or improvement on semiconductor device, equipment, element, or method;
- 2 design or improvement on manufacture procedure or equipment;
- ③ improvement on manufacture method;
- any form of intellectual or practical invention-creation in the semiconductor industry or scientific field development.

I agree that SMIC has complete right in said invention-creation, and SMIC can use and dispose it. Even any related invention-creation as described above that is made within two (at least two years) years since the termination of my employment from SMIC still belongs to SMIC. (SMIC will reward the inventor according to the contribution of the invention achievement.)

SMIC requires that an employee should not infringe other company's intellectual property, or illegally use other's intellectual property (including information, document, or any intellectual achievement related to IP) without authorization.

I agree that I'll not infringe other's intellectual property, or illegally use other's intellectual property (including information, document, or any intellectual achievement related to IP) without authorization. I'll not plagiarism, imitate, infringe, copy a third party's patent right, exclusive right of trademark, or copy right, or carry out any actions against law.

Signature	 Date	7.
Signature	 Date	20 1 2 2 2 2 2 2 2 2 2 2 2 2 2 2 2 2 2 2



Commissioner for Patents
United States Patent and Trademark Office
P.O. Box 1450
Alexandria, VA 22313-1450
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TOWNSEND AND TOWNSEND AND CREW, LLP TWO EMBARCADERO CENTER EIGHTH FLOOR SAN FRANCISCO CA 94111-3834

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JUL 1 3 2009

In re Application of Xiao and Chen

OFFICE OF PETITIONS

Application No.: 12/258,956 Filed: October 27, 2008

: DECISION ACCORDING : RULE 47(a) STATUS

Attorney Docket No: 021653-024600US

Attorney Docket No: 021055-02400005

For: METHOD AND SYSTEM FOR FORMING CONDUCTIVE BUMPING WITH COPPER INTERCONNECTION

This is in response to the petition under 37 CFR 1.47(a), filed June 17, 2009.

The petition is **GRANTED**.

The above-identified application and papers have been reviewed and found in compliance with 37 CFR 1.47(a). This application is hereby accorded Rule 1.47(a) status.

The above-cited application was filed on October 27, 2008, without a properly executed oath or declaration. Accordingly, a "Notice to File Missing parts of Nonprovisional Application" (the "Notice") was mailed on November 17, 2008, requiring an executed oath or declaration and a surcharge for the late filing of the oath or declaration among other items. The instant petition was filed on June 17, 2009, with a request for an extension of time within the fifth month.

Petitioner has shown that inventor Chen cannot be located to execute the declaration and join the above-identified application and papers have been reviewed and found in compliance with 37 CFR 1.47(a). This application is hereby accorded Rule 1.47(a) status.

As provided in Rule 1.47(c), this Office will forward notice of this application's filing to the non-signing inventors at the addresses given in the petition. Notice of the filing of this application will also be published in the Official Gazette.

This application will be directed to the Office of Patent Application Processing for further processing.

Telephone inquiries concerning this decision should be directed to the undersigned at (571) 272-3222.

Kenya A. McLaughlin Petitions Attorney Office of Petitions



UNITED STATES PATENT AND TRADEMARK OFFICE

Commissioner for Patents United States Patent and Trademark Office P.O. Box 1450 Alexandria, VA 22313-1450 www.uspto.gov

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OFFICE OF PETITIONS

: : LETTER

Guo Qing Chen 1044 Euclid 5 Tucson, AZ 85719

In re Application of

Xiao and Chen

Application No.: 12/258,956

Filed: October 27, 2008

Attorney Docket No: 021653-024600US

For: METHOD AND SYSTEM FOR FORMING CONDUCTIVE BUMPING

WITH COPPER INTERCONNECTION

Dear Inventor Chen:

You are named as a joint inventor in the above-identified United States patent application filed under the provisions of 35 U.S.C. 116 (United States Code) and 37 CFR 1.47(b), Rules of Practice in Patent Cases. Should a patent be granted on the application you will be designated therein as a joint inventor.

As a joint inventor, you are entitled to inspect any paper in the file wrapper of the application, order copies of all or any part thereof (at a prepaid cost per 37 CFR 1.19) or make your position of record in the application. Alternatively, you may arrange to do any of the preceding through a registered patent attorney or agent presenting written authorization from you. If you care to join the application, counsel of record (see below) would presumably assist you. Joining in the application would entail the filing of an appropriate oath or declaration by you pursuant to 37 CFR 1.63.

Telephone inquiries regarding this communication should be directed to Petitions Attorney Kenya A. McLaughlin at (571) 272-3222. Requests for information regarding your application should be directed to the File Information Unit at (703) 308-2733. Information regarding how to pay for and order a copy of the application, or a specific paper in the application, should be directed to Certification Division at (703) 308-9726 or 1-800-972-6382 (outside the Washington D.C. area).

Kenya A. McLaughlin

Petitions Attorney

Office of Petitions

TOWNSEND AND TOWNSEND AND CREW, LLP TWO EMBARCADERO CENTER EIGHTH FLOOR SAN FRANCISCO CA 94111-3834

> PATENT REEL: 026025 FRAME: 0403

RECORDED: 03/25/2011